

Multilayer Ceramic Chip Capacitors

CGA6P4NP02J333J250AA



TDK item description ? CGA6P4NP02J333J250AA

Applications Automotive Grade

Feature

- Mid Mid Voltage (100 to 630V)
- 150°C High Temperature Application
- AEC-Q200 AEC-Q200

Series CGA6(3225) [EIA 1210]

Status Production



Images are for reference only and show exemplary products.

PDF file of this page

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- Documents**
- Catalog
 - Specification
 - RoHS Certificate
 - SVHC/REACH Certificate Update
 - Selection Guide for Automotive MLCC New
 - Sample Kits
 - Characterization Sheet

Size	
Length(L)	3.20mm ±0.40mm
Width(W)	2.50mm ±0.30mm
Thickness(T)	2.50mm ±0.30mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	2.00mm to 2.40mm
Recommended Land Pattern (PB)	1.00mm to 1.20mm
Recommended Land Pattern (PC)	1.90mm to 2.50mm

Electrical Characteristics	
Capacitance	33nF ±5%
Rated Voltage	630VDC
Temperature Characteristic ?	NP0(0±30ppm/°C)
Q (Min.)	1000
Insulation Resistance (Min.)	10000MΩ

Other	
Soldering Method	Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)



CGA6P4NP02J333J250AA

Change settings

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Capacitance

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DC Bias Characteristic

CGA6P4NP02J333J250AA

Change settings

Temperature Characteristic

CGA6P4NP02J333J250AA(No Bias) CGA6P4NP02J333J250AA(DC Bias = 315V)

Change settings

Ripple Temperature Rising

no data available

Change settings



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- Power Supplies >
- Magnets >
- Flash Storages >
- Wireless Power Transfer >
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